TEXAS INSTRUMENTS

Bill of Materials

TI DESIGNS

TIDC-CC3200MODLAUNCHXL BOM Revision - 1.0 Date : 11-November -2014

Item	Qty	Reference	Value	Manufacturer	Manufacturer Part Number	Description
1	44	R10 R12 R22 R31 R36 R75 R97 R98 R99 R101 R102 R103 R104 R106 R107 R108 R109 R110 R113 R231 R237 R277 R278 R279 R280 R284 R285 R286 R287 R288 R289 R290 R291 R292 R293 R294 R295 R309 R310 R311 R312 R313 R335 R341	0 R	Yageo	RC0402JR-070RL	RES C SMD 0402 0ohm 5% GP/HF
2	1	C54	33nF	MURATA	GRM155R71A333KA01D	CAP CER 33nF 10% 10V SMD 0402 GP/HF X7R T=0.5mm
3	14	C50 C51 C52 C55 C56 C57 C58 C68 C69 C70 C72 C75 C76 C77	0.1uF	Murata	GRM155R61A104KA01D	CAP CER 100nF 10% 10V SMD 0402 GP/HF X5R 0.5mm
4	1	C64	1.0pF	WALSIN	0402N1R0C500LT	CAP CER 1.0pF +-0.25pF 50V SMD 0402 GP/HF NPO T=0.55mm
5	1	R345	1.5Kohm	YAGEO	RC0402JR-071K5L	RES C SMD 0402 1.5Kohm 5% GP/HF
6	2	C65 C71	100uF	MURATA	GRM32ER60J107ME20L	CAP CER 100uF 20% 6.3V SMD 1210 GP/HF X5R 2.5mm
7	8	R4 R7 R13 R212 R213 R214 R226 R347	100k	Yageo	RC0402FR-07100KL	RES C SMD 0402 100Kohm 1% GP/HF
8	1	R225	100R	Yageo	RC0402JR-07100RL	RES C SMD 0402 100ohm 5% GP/HF
9	18	R30 R32 R34 R207 R208 R209 R210 R211 R302 R314 R315 R318 R319 R322 R325 R328 R329 R342	10k	Yageo	RC0402FR-0710KL	RES C SMD 0402 10Kohm 1% GP/HF
10	1	C73	10pF	WALSIN	0402N100C500LT	CAP CER 10pF +-0.25pF 50V SMD 0402 GP/HF NPO 0.5mm
11	4	C32 C33 C63 C66	10uF	TDK	C1608X5R0J106MT	CAP CER 10uF 20% 6.3V SMD 0603 GP/HF X5R T=0.8mm
12	1	L11	10uH	MURATA	LQM21FN100M70L	IND C 10uH 20% 100mA 0.6ohm SMD 0805 GP/HF
13	1	C31	15pF	WALSIN	0402N150J250LT	CAP CER 15pF 5% 25V SMD 0402 GP/HF NPO T =0.55mm
14	1	Y1	6MHz-XTAL-4	TXC	9C06000086	XTAL 6MHz 30ppm 20pF 150ohm SMD
15	2	R168 R169	1K	Yageo	RC0402FR-071KL	RES C SMD 0402 1Kohm 1% GP/HF
16	1	R35	2.2K	WALSIN	WR04X222 JTL	RES C SMD 0402 2.2Kohm 5% GP/HF
17	7	R9 R64 R69 R70 R94 R95 R326	270	YAGEO	RC0603JR-07270RL	RES C SMD 0603 270ohm 5% GP
18	2	C59 C60	30pF	WALSIN	0402N300J500CT	CAP CER 30pF 5% 50V SMD 0402 GP/HF NPO T=0.5mm
19	2	R28 R343	28ohm	YAGEO	RC0402FR-0728RL	RES C SMD 0402 28ohm 1% GP/HF
20	2	R172 R173	3.3K	TA-I	RM04JTN332	RES C SMD 0402 3.3Kohm 5% GP/HF
22	1	L4	3.6nH	TAIYO	HK10053N6S-T	IND C 3.6nH 0.3nH 300mA 0.2ohm Q=8 SMD 0402 GP/HF
23	1	R55	30.1K	YAGEO	RC0402FR-0730K1L	RES C SMD 0402 30.1Kohm 1% GP/HF
24	15	R303 R304 R305 R306 R316 R317 R320 R321 R323 R324 R327 R330 R331 R332 R333	33ohm	Yageo	RC0402JR-0733RL	RES C SMD 0402 33ohm 5% GP/HF
25	1	R338	470ohm	Yageo	RC0402JR-07470RL	RES C SMD 0402 470ohm 5% GP/HF
26	1	R56	52.3K	TA-I	RM04FTN5232	RES C SMD 0402 52.3Kohm 1% GP/HF

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27	2	FB11 FB12	60R	CHILISIN	UPB160808T-600Y-N	BEAD C 60ohm 25% 4A 0.02ohm SMD 0603 GP/HF
28	1	U2	93LC46B-I/MS	Microchip	93LC46BT-I/ST	Serial EEPROM 2.5-5.5V 16-bit word size SMD
29	1	E1	AH316M245001-T	Taiyo_Yuden	AH316M245001-T	2.4G wifi ANT
30	1	U10	BMA222	Bosch	BMA222E	3-AXIS ACCELEROMETER DIGITAL SMD
31	4	Q7 Q8 Q9 Q10	BSS138LT3G	On Semi	BSS138LT3G/BSS138LT1G	MOSFET N-CH 50V 200MA SOT-23
32	1	J1	CONN_MICRO_USB	POWERWAY	SUA-160M3B-L2E-TR1	CONN MICRO USB B 5PIN 0.65mm SMD FEMALE RT GP
33	2	J22 J23	CONN_RCPT_10x2	Samtec	SSQ-110-03-T-D	CONN RCPT .100" 20POS DUAL TIN
34	1	J18	CONN_U.FL	FOXCONN	KK23017-01-7F	HEADER RF 1*1PORT D0.5/D2.0mm SMD MALE ST GP/HF
35	1	D9	DIODE	DIODES	DFLS130L-7	DIODE SBD 30V 1.0A SMD POWER DI123 GP/HF
36	1	U5	FT2232D	FTDI	FT2232D	IC PER 4.35~5.25V SMD LQFP48 GP USB CONTROLLER FT2232D
37	4	J6 J7 J19 J20	HEADER_3	CVILUX	CH31032V200	HEADER PIN 3P 2.54mm DIP MALE ST GP
38	13	J2 J3 J4 J8 J9 J10 J11 J12 J13 J14 J15 J16 J17	JUMPER MALE	CVILUX	CH31022V202	HEADER PIN 1*2P 2.54mm DIP MALE ST GP
39	2	D2 D5	LED_G	LITEON	LTST-C190KGKT	LED CHIP 35mcd G 571nm 2P SMD 1.6*0.8mm GP/HF LTST-C190KGKT
40	2	D4 D7	LED_R	LITEON	LTST-C190KRKT	LED CHIP 45~180mcd R 624~638nm 2P SMD 1.6*0.8mm GP/HF
41	2	D1 D6	LED_Y	LITEON	LTST-C190KFKT	LED CHIP 60mcd O 605nm 2P SMD 1.6*0.8mm GP/HF LTST-C190KFKT
42	1	J24	MM8030-2610RJ3	MURATA	MM8030-2610RJ3	HEADER RF 1*1PORT D=0.5/1.35mm SMD FEMALE ST GP
43	1	Q11	SI2323DS-T1-GE3	Vishay	SI2323DS-T1-GE3	MOSFET P-CH 20V 3.7A SOT23-3
44	2	U4 U9	SN74LVC125APWR	TI	SN74LVC125APWRG4	IC BUFFERS 1.65~3.6V SMD TSSOP14 GP/HF SN74LVC125APWRG4
45	1	U7	SN74LVC126APWR	TI	SN74LVC126APWR	IC CMOS 1.65~3.6V SMD TSSOP14 GP/HF SN74LVC126APWR
46	2	U11 U12	SN74LVC1T45D	TI	SN74LVC1T45DBVR	IC TRANSCEIVER 1.65~5.5V SMD SOT23-6 GP/HF SN74LVC1T45DBVR
47	3	SW1 SW2 SW3	SW-4PIN	POWERWAY	DTST-61K-Q	SW TACT 50mA 12V DIP ST GP
48	1	U6	TMP006	TI	TMP006AIYZFR	IC SENSOR 3.3V SMD WCSP-8 TEMP GP/HF TMP006AIYZFR
49	1	U8	TPS61097-33DBVR	TI	TPS61097-33DBVT	IC REG BST SYNC 3.3V .1A SOT23-5
50	1	U3	TPS73701	TI	TPS73701DCQR	IC REG 1.2~5.5V 1A SMD SOT223-6 GP/HF TPS73701DCQR
51	2	D13 D14	V5.5MLA	LITTELFUSE	V5.5MLA0402NR	VARISTOR 5.5V 20A 2P SMD 0402 GP
52	11		JUMPER FEMALE	FOXCONN	SJ2520H-A0	CONN JUMPER 2P 2.54mm FEMALE RT GP
53	1		PCB	ZHENDING	308.01741.015	81.3mm*50.3mm, 4 layers, through hole
54	1	R8	2.7K	Yageo	RC0402JR-072K7L	RES C SMD 0402 2.7Kohm 5% GP/HF
55	1	U1	CC3200 module	FOXCONN	95.1341T00	CC3200 LGA module

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